

# LOCTITE ABLESTIK 8390P

April 2014

## PRODUCT DESCRIPTION

LOCTITE ABLESTIK 8390P provides the following product characteristics:

<b>Technology</b>	Epoxy
<b>Appearance</b>	Silver
<b>Cure</b>	Heat cure
<b>Product Benefits</b>	<ul style="list-style-type: none"> <li>• Low resin bleed</li> <li>• Electrically conductive</li> <li>• In-line oven snap cure</li> <li>• Low voiding during cure</li> <li>• Moderately stress absorbing</li> <li>• Consistent bondline control with minimal die tilt</li> <li>• Excellent dispensability, minimal tailing and stringing</li> </ul>
<b>Application</b>	Die attach
<b>Filler Type</b>	Silver
<b>Substrates</b>	Silver-plated copper leadframes, Palladium-plated copper leadframes and Silver-plated Alloy 42 leadframes
<b>pH</b>	7.4

LOCTITE ABLESTIK 8390P die attach adhesive is specially formulated for small to medium size packages. It is suitable for die sizes up to 8 x 8 mm.

## TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	≥3.8
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):	
Speed 5 rpm	10,000
Work Life @ 25°C, hours	48
Shelf Life @ -40°C (from date of manufacture), days	365

## TYPICAL CURING PERFORMANCE

### Recommended Snap Cure Schedule

7-Zone Oven	
Temp per zone: 170°C, 160°C, 160°C, 160°C, 175°C, 190°C, 200°C	
Total Time, seconds	60
N2 Flow, liters/minute	10
N2 Preheat temp, °C	250

### Alternative Cure Schedule

15 minutes @ 175°C

### Weight Loss on Cure

10 x 10 mm Si die on glass slide, %	0.7
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The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

## TYPICAL PROPERTIES OF CURED MATERIAL

### Physical Properties

Coefficient of Thermal Expansion :	
Below Tg, ppm/°C	83
Above Tg, ppm/°C	165
Glass Transition Temperature (Tg) by TMA, °C	60
Thermal Conductivity @ 121°C, W/(m-K)	1.0
Tensile Modulus, DMTA :	
@ -65 °C	N/mm <sup>2</sup> 3,600 (psi) (520,000)
@ 25 °C	N/mm <sup>2</sup> 2,600 (psi) (380,000)
@ 150 °C	N/mm <sup>2</sup> 220 (psi) (32,000)
@ 250 °C	N/mm <sup>2</sup> 140 (psi) (20,000)
Extractable Ionic Content, @ 100°C ppm:	
Chloride (Cl-)	<10
Sodium (Na+)	<10
Potassium (K+)	<5
Water Extract Conductivity, µmhos/cm	70
Weight Loss @ 300°C, %:	
Snap Cured	0.92
Oven Cured	0.42
Moisture Absorption @ Saturation, wt.% @ 85°C/85%RH	@ 0.87

### Electrical Properties

Volume Resistivity, ohms-cm	≤0.01
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## TYPICAL PERFORMANCE OF CURED MATERIAL

### Miscellaneous

Die Shear Strength:	
2 x 2 mm Si die @ 25 °C, kg-f:	
on Ag/Cu LF	15.1
on Bare Cu LF	17.6
on Pd/Ni/Cu LF	15.0
5 x 5 mm Si die @ 250 °C, kg-f:	
on Ag/Cu LF	7.0
on Bare Cu LF	6.7
on Pd/Ni/Cu LF	6.1

### Chip Warpage vs Post Cure Thermal Process:

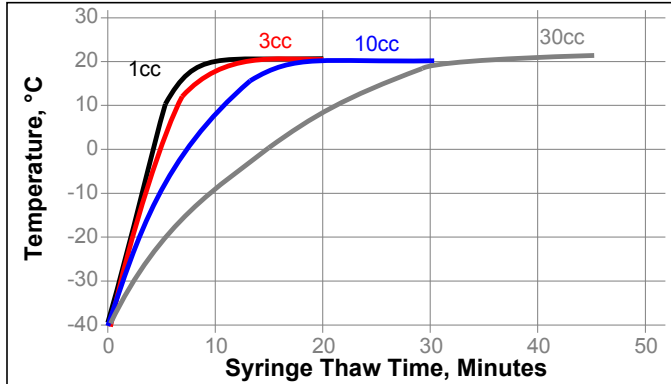
11.2 x 11.2 x 0.38 mm Si die on 0.2 mm thick Ag/Cu LF, µm:	
Post Cure	17
Plus Wirebond (1 minute @ 250°C)	16
Plus Post Mold Bake (4 hours @ 175°C)	21
12.7 x 12.7 x 0.38 mm Si die on 0.2 mm thick Ag/Cu LF, µm:	
Post Cure	54
Plus Wirebond (1minute @ 250°C)	50
Plus Post Mold Bake (4hours @ 175°C)	55

**GENERAL INFORMATION**

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

**THAWING:**

1. Allow container to reach room temperature before use.
2. After removing from the freezer, set the syringes to stand vertically while thawing.
3. Refer to the Syringe Thaw time chart for the thaw time recommendation.
4. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
5. DO NOT re-freeze. Once thawed to -40°C, the adhesive should not be re-frozen.

**DIRECTIONS FOR USE**

1. Thawed material should immediately be placed on dispense equipment for use.
2. If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.
3. Adhesive must be completely used within the product's recommended work life.
4. Silver-resin separation may occur if the adhesive is left out at room temperature, beyond the recommended work life.
5. Apply enough adhesive to achieve a 25 to 50 µm wet bondline thickness, dispensed with approximately 25 to 50 % filleting on all sides of the die.
6. Alternate dispense amounts may be used depending on the application requirements.
7. Star or crossed shaped dispense patterns will yield fewer bondline voids than the matrix style of dispense pattern.

**Not for product specifications**

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

**STORAGE:**

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

**Conversions**

(°C x 1.8) + 32 = °F  
 kV/mm x 25.4 = V/mil  
 mm / 25.4 = inches  
 N x 0.225 = lb  
 N/mm x 5.71 = lb/in  
 psi x 145 = N/mm<sup>2</sup>  
 MPa = N/mm<sup>2</sup>  
 N·m x 8.851 = lb·in  
 N·m x 0.738 = lb·ft  
 N·mm x 0.142 = oz·in  
 mPa·s = cP

**Disclaimer****Note:**

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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